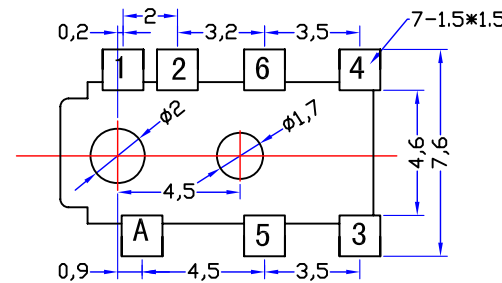
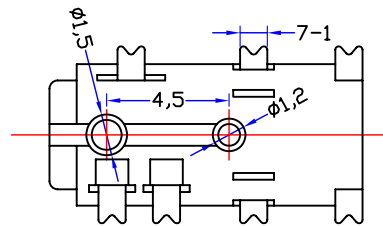
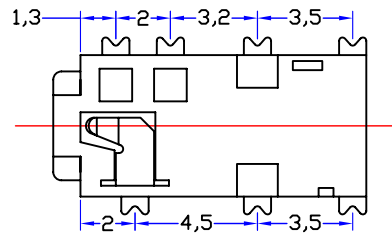
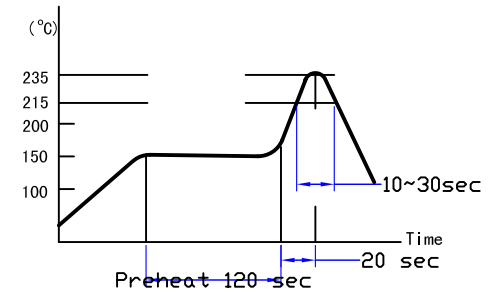


SCHEMATIC



P. C. B TERMINAL POSITION



REFLOW SOLDERING CONDITIONS

No	Parts	Material	Qty	Finish	Specifications	PJ-240-SMD TITLE: PHONE JACK UNLESS OTHERWISE SPECIFIED TOLERANCE ±0.1 ANGLE TOL ±30" UNIT: mm SCALE: DRAWN: jia DATE: 2006-06-18 CHECKED: DATE: APPROVED: DATE:
1	Body	PA6T+30%Fider	1	94V-0	Rating: DC 12V 0.5A	
2	Chip Terminal	t:0.20 Cu-TI Alloy	7	Ep-Cu/Ni 1, Au 1(Silver Plating)	Contact Resistance: 30m ohm max	
					Insulation Resistance: 100M ohm at 500V DC	
					Dielectric Strength: AC 500V for 1 Minute	
					Insertion & Extraction Force:0.2-2.0kgf	
					Life: 5.000 Cycles	
					Taping: 1.000 Pcs/Reel	
XYFW(www.cnxyfw.com)				